Silicon PNP Epitaxial

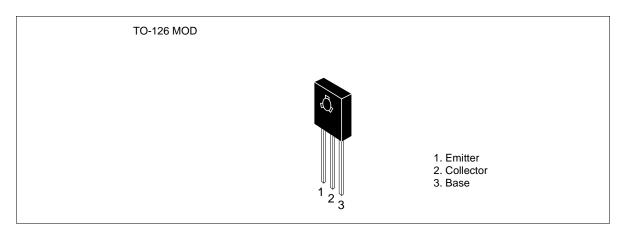
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ADE-208-853 (Z) 1st. Edition Sep. 2000

Application

Low frequency power amplifier complementary pair with 2SC1212 and 2SC1212A

Outline



Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

		Ratings		
Item	Symbol	2SA743	2SA743A	Unit
Collector to base voltage	V_{CBO}	-50	-80	V
Collector to emitter voltage	V _{CEO}	-50	-80	V
Emitter to base voltage	V_{EBO}	-4	-4	V
Collector current	I _c	-1	– 1	А
Collector power dissipation	P _c	0.75	0.75	W
	P _c *1	8	8	
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

Note: 1. Value at $T_c = 25^{\circ}C$.

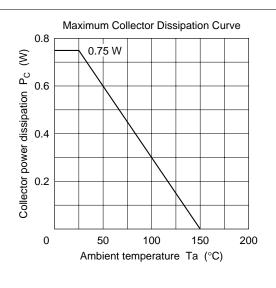


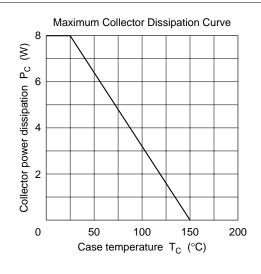
Electrical Characteristics (Ta = 25°C)

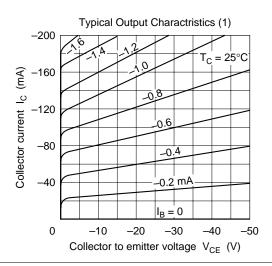
		2SA7	43		2SA743A				
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-50	_	_	-80	_	_	V	$I_{\rm C} = -1 \text{ mA}, I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-50	_	_	-80	_	_	V	$I_{\rm C}$ = -10 mA, $R_{\rm BE}$ = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-4	_	_	-4	_	_	V	$I_{E} = -1 \text{ mA}, I_{C} = 0$
Collector cutoff current	I _{CER}	_	_	-20	_	_	_	μΑ	$V_{CE} = -50 \text{ V}, R_{BE} = 1$ $k\Omega$
	I _{CER}	_	_	_	_	_	-20	_	$\overline{V_{CE} = -80 \text{ V, R}_{BE} = 1}$ $k\Omega$
DC current tarnsfer ratio	h _{FE} *1	60	120	200	60	120	200		$V_{CE} = -4 \text{ V}, I_{C} = -50 \text{ mA}$
	h _{FE}	20	_	_	20	_	_	_	$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}$ (pulse)
Base to emitter voltage	V_{BE}	_	-0.65	-1.0	_	-0.65	1.0	V	$V_{CE} = -4 \text{ V}, I_{C} = -50 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	-0.75	-1.5	_	-0.75	-1.5	V	$I_{\rm C} = -1 \text{ A}, I_{\rm B} = -0.1 \text{ A}$
Gain bandwidth product	f _T	_	120	_	_	120	_	MHz	$V_{CE} = -4 \text{ V}, I_{C} = -30 \text{ mA}$

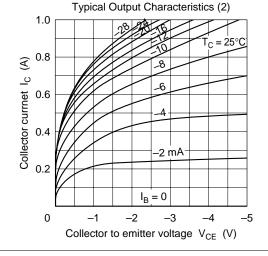
Note: 1. The 2SA743 and 2SA743A is grouped by $h_{\rm FE}$ as follows.

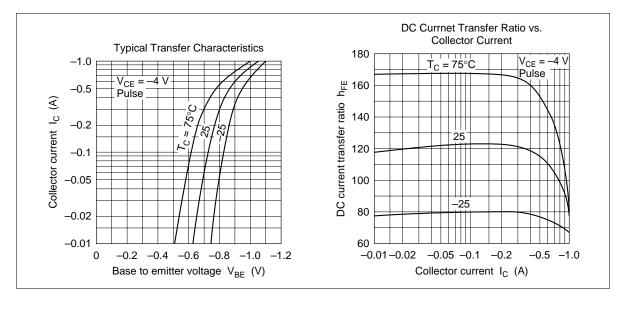
В	С
60 to 120	100 to 200





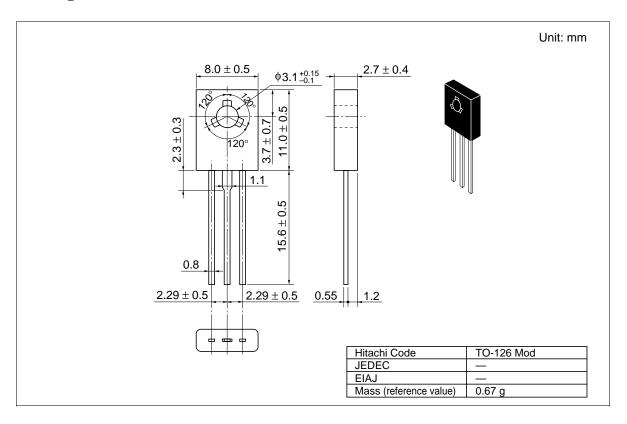






	2SA743, 2SA743A
Package Dimensions	

Package Dimensions



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